

10/069053

FILED UNDER 35 U.S.C. 371

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10069053	FILING DATE 07/08/2002	CLASS 528	SUBCLASS 44	GAU 171 172	EXAMINER GORE
**APPLICANTS: Fujinawa Tohiru; Yusa Masami; Nomura Satoyuki; Ono Hiroshi; Watanabe Itsuo; Arifuku Motohiro; Kanazawa Hohiko;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/05763 08/25/1999					
**FOREIGN APPLICATIONS VERIFIED: JAPAN 11-238409 08/25/1999 JAPAN 2000-92978 03/28/2000					
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PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO. 566.41199X00			
Verified and Acknowledged Examiners's initials					
TITLE : Wiring-connecting material and process for producing circuit board with the same <small>U.S. DEPT. OF COMM./PAT. & TM.; PTO-459L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for I.O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg	Figs. Drwg
		Print Fig	
<input type="checkbox"/> TERMINAL DISCLAIMER		Applicant's Examiner	
		PREPARED FOR ISSUE	
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